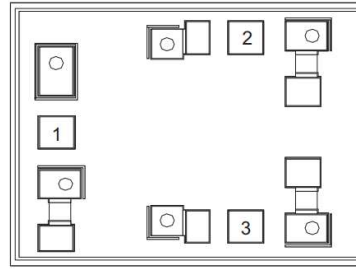


Performance

- Frequency: 6~18GHz
- Insertion loss: 0.6dB
- Chip size: 1.01*0.80*0.1mm

Function Diagram

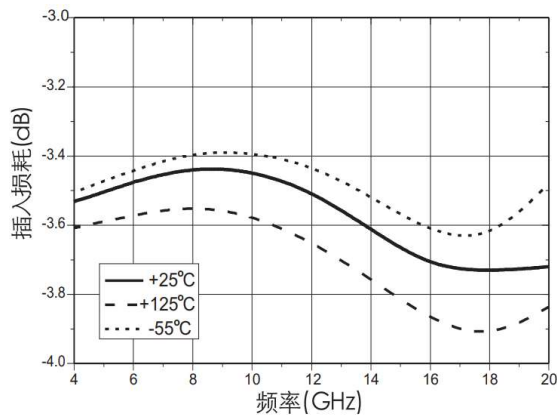


Electrical Specifications (Ta=+25°C, 50Ω system)

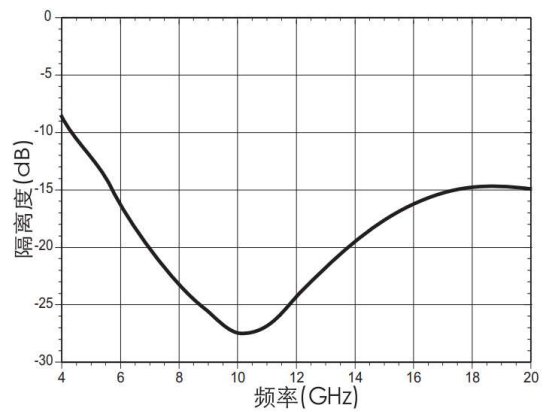
Parameter	Min	Typical	Max	Unit
Frequency Range	6~18			GHz
Insertion Loss	-	0.6	1.0	dB
Insertion Loss Ripple	-	±0.3	-	dB
Isolation	15	20	-	dB
Input Return Loss	13	18	-	dB
Output Return Loss	15	18	-	dB

Test Curves

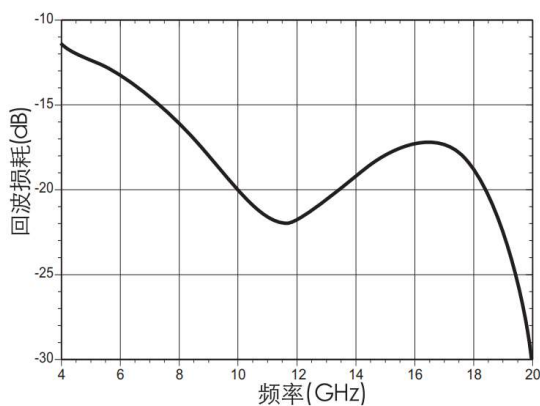
Insertion loss vs. Freq



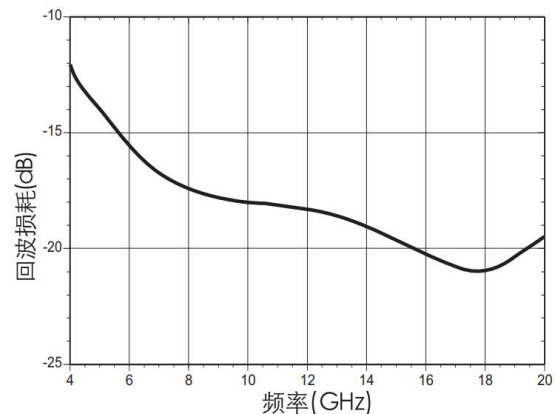
Isolation vs. Freq



Input Return Loss vs. Freq



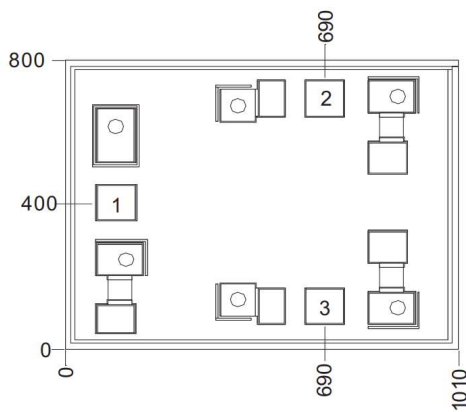
Output Return Loss vs. Freq



Absolute Max Ratings

Parameter	Value
Input Signal Power	+37dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C
Junction Temperature	175°C
Static protection Grade (HBM)	Class 1A

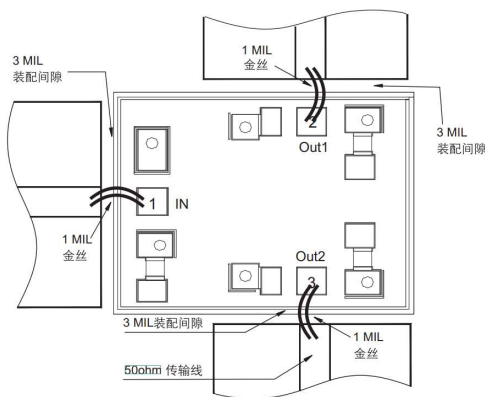
Outline Size



Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated
Pads size: 100*100 um
5. Don't bonding on thru holds
6. Tolerance: ±50um

Assembly Diagram



Bonding Definition

No.	Symbol	Description
1	IN	RF input, 50ohm
2,3	Out1, Out2	RF output, 50ohm
	GND	Bottom must be grounded